INTERNATIONAL STANDARD



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Surface chemical analysis — Secondary-ion mass spectrometry — Method for depth profiling of boron in silicon

Analyse chimique des surfaces — Spectrométrie de masse des ions secondaires — Dosage du bore dans le silicium par profilage d'épaisseur

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Foreword

ISO (the International Organization for Standardization) is a worldwide federation of national standards bodies (ISO member bodies). The work of preparing International Standards is normally carried out through ISO technical committees. Each member body interested in a subject for which a technical committee has been established has the right to be represented on that committee. International organizations, governmental and non-governmental, in liaison with ISO, also take part in the work. ISO collaborates closely with the International Electrotechnical Commission (IEC) on all matters of electrotechnical standardization.

International Standards are drafted in accordance with the rules given in the ISO/IEC Directives, Part 3.

Draft International Standards adopted by the technical committees are circulated to the member bodies for voting. Publication as an International Standard requires approval by at least 75 % of the member bodies casting a vote.

Attention is drawn to the possibility that some of the elements of this International Standard may be the subject of patent rights. ISO shall not be held responsible for identifying any or all such patent rights.

International Standard ISO 17560 was prepared by Technical Committee ISO/TC 201, *Surface chemical analysis*, Subcommittee SC 6, *Secondary ion mass spectrometry*.

Annex A of this International Standard is for information only PREVIEW (standards.iteh.ai)

Introduction

This International Standard was prepared for the quantitative depth profiling of boron in silicon by secondary-ion mass spectrometry (SIMS).

For quantitative depth profiling, calibration is necessary both for the concentration and the depth scales of the profile measured. A procedure for the determination of boron in silicon has been established as an International Standard, ISO 14237. Thus, the calibration of boron atomic concentration is performed by following ISO 14237.

In this International Standard, standard procedures are described for depth profiling of boron in single-crystal, poly-crystal or amorphous silicon using SIMS and for depth scale calibration using stylus profilometry or optical interferometry.

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Surface chemical analysis — Secondary-ion mass spectrometry — Method for depth profiling of boron in silicon

1 Scope

This International Standard specifies a secondary-ion mass spectrometric method using magnetic-sector or quadrupole mass spectrometers for depth profiling of boron in silicon, and using stylus profilometry or optical interferometry for depth scale calibration. This method is applicable to single-crystal, poly-crystal or amorphous-silicon specimens with boron atomic concentrations between 1×10^{16} atoms/cm³ and 1×10^{20} atoms/cm³, and to crater depths of 50 nm or deeper.

2 Normative reference

The following normative document contains provisions which, through reference in this text, constitute provisions of this International Standard. For dated references, subsequent amendments to, or revisions of, this publication do not apply. However, parties to agreements based on this International Standard are encouraged to investigate the possibility of applying the most recent edition of the normative document indicated below. For undated references, the latest edition of the normative document referred to applies. Members of USO and IEC maintain registers of currently valid International Standards.

(standards.iteh.ai) ISO 14237:2000, Surface chemical analysis — Secondary-ion mass spectrometry — Determination of boron atomic concentration in silicon using uniformly doped materials

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3 Symbols and abbreviated termsbafb1c140f9/iso-17560-2002

- C_i total boron atomic concentration in measurement cycle i, expressed in atoms per cubic centimetre (atoms/cm³)
- C_i^{10} atomic concentration of the boron isotope with mass number 10 in measurement cycle *i*, expressed in atoms per cubic centimetre (atoms/cm³)
- C_i^{11} atomic concentration of the boron isotope with mass number 11 in measurement cycle *i*, expressed in atoms per cubic centimetre (atoms/cm³)
- d_i depth measured in measurement cycle *i*, expressed in micrometres (μ m) or nanometres (nm)
- d_t crater depth, expressed in micrometres (μ m) or nanometres (nm)
- I_i^{10} ion intensity of the boron isotope with mass number 10 in measurement cycle i
- I_i^{11} ion intensity of the boron isotope with mass number 11 in measurement cycle *i*
- I_i^{Si} ion intensity of silicon matrix in measurement cycle i
- J_i^{10} boron to silicon ion intensity ratio for the boron isotope with mass number 10 in measurement cycle *i*
- J_i^{11} boron to silicon ion intensity ratio for the boron isotope with mass number 11 in measurement cycle *i*
- $J_{\rm BG}^{10}$ mean background boron to silicon ion intensity ratio for the boron isotope with mass number 10 in measurement cycle *i*

- $J_{\rm BG}^{11}$ mean background boron to silicon ion intensity ratio for the boron isotope with mass number 11 in measurement cycle *i*
- N total number of measurement cycles
- T total measurement time, expressed in seconds (s)
- t_i^{B} starting time of boron-ion acquisition in measurement cycle *i*, expressed in seconds (s)
- Δt^{B} duration of boron-ion acquisition in each measurement cycle, expressed in seconds (s)
- δ mass discrimination correction factor
- λ wavelength of the light for optical interferometry, expressed in micrometres (µm) or nanometres (nm)
- RSF^{work} working relative-sensitivity factor
- SIMS secondary-ion mass spectrometry

4 Principle

An oxygen-ion beam or caesium-ion beam is scanned over the specimen surface and the emitted secondary ions of boron and silicon from a gated region within the area scanned by the ion beam are detected and mass-analysed. The intensities of these mass-analysed signals are monitored as a function of sputtering time. The depth of the crater formed by the ion beam is measured by stylus profilometry or optical interferometry for depth scale calibration.

NOTE Optical interferometry is generally applicable to crater depths in the range from 0,5 µm to 5 µm.

5 Reference materials

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ISO 17560:2002

5.1 Reference materials for determination of relative-sensitivity factors

Follow clause 4 of ISO 14237:2000.

5.2 Reference materials for calibration of depth scale

For stylus profilometry calibration, certified reference materials or reference materials which are traceable to certified reference materials shall be used.

6 Apparatus

6.1 Secondary-ion mass spectrometer

As specified in clause 5 of ISO 14237:2000.

6.2 Stylus profilometer

Use a stylus profilometer with a sensitivity and tip shapes suitable for the crater shapes to be measured.

6.3 Optical interferometer

Use an optical interferometer with a sensitivity and functions suitable for the crater shapes to be measured.

7 Specimen

The specimen shall be cut to an appropriate size for analysis and degreased and washed if necessary.

NOTE The accuracy of crater depth measurement is largely influenced by surface roughness. A mirror-polished wafer is preferable when accurate determination of the depth scale is necessary.

8 Procedures

8.1 Adjustment of secondary-ion mass spectrometer

8.1.1 For oxygen-ion beam use, see Table 1. For caesium-ion beam use, see Table 2. Other conditions not shown here shall be set in accordance with the manufacturer's instructions or a local documented procedure.

| Primary-ion species | O ₂ + |
|-------------------------|--------------------------------------------------------------------------------|
| Secondary-ion polarity | Positive |
| Primary-ion scan region | > three times the linear dimension of the analysed region in all directions |
| Analysed region | Centred in the primary-ion scan region |

Table 1 — Measurement conditions for oxygen-ion beam

Table 2 — Measurement conditions for caesium-ion beam

| Primary-ion species | Cs ⁺ |
|----------------------------------------|--------------------------------------------------------------------------------|
| Secondary-ion polarityStanda | Negative teh.ai) |
| Primary-ion scan region | > three times the linear dimension of the analysed(region in all directions |
| Analysed regionards.iteh.ai/catalog/st | Centred in the primary-lon scan begion |

8.1.2 For the primary-ion beam, the beam current and scan region can be varied from specimen to specimen (see 8.5.2). However, when oxygen gas is introduced into the chamber during oxygen-beam irradiation, the oxygen pressure and all the primary-ion beam irradiation conditions shall be the same for the measurements on all specimens.

8.2 Optimizing the secondary-ion mass spectrometer settings

8.2.1 Set the required instrument parameters and align the ion optics in accordance with the manufacturer's instructions or a local documented procedure.

8.2.2 Ensure the stability of the primary-ion current and the mass spectrometer in accordance with the manufacturer's instructions or a local documented procedure.

8.2.3 For a mass spectrometer whose transmission can be varied, use the same transmission for the measurements on both reference materials and test specimens.